SEMI AUX001-1218
LIST OF WAFER SUPPLIER IDENTIFICATION CODES

NOTE: The material in this Auxiliary Information is referenced by Documents in the SEMI Standards Materials and Traceability volumes. It replaces Appendices in SEMI M12, SEMI M13, and SEMI T5.

The codes listed in Tables 1 and 2 are included for the convenience of the industry and are maintained by SEMI. Changes or additions to this table are the responsibility of the company listed, and should be addressed to:

Standards Coordinator, Materials Committee
SEMI
673 S. Milpitas Blvd.
Milpitas, CA 95035

Please note that some companies listed no longer exist. These tables are frequently updated.

Table 1 Supplier Identification Codes Sorted by Supplier

Supplier	*Code*
II-VI Incorporated	EV
AETS Co., Ltd.	AT
Applied Materials	AP
American Silicon Products	AS
American Telephone and Telegraph Lucent Technologies	WE
American Xtal Technology	XT
Ametec	AM
Atecom Technology Co., Ltd.	AC
Bertram Laboratories	BL
Canon	EL
Cincinnati Milacron	CM
Chongqing Advanced Silicon Technology Co., Ltd	YZ
Cominco Electronic Materials	CO
Covalent Material Corporation	CV
GlobalWafersJapan Co., Ltd.	TC
Cree, Inc.	CI
Crystal Specialties International	CX
CrystalQ	CQ
Crysteco	CR
Delco	DE
Diversified Substrates	DS
Dow Corning	DC
Dowa Mining	DW
D&X Co., Ltd.	DX
Dynamit Nobel Italy	DN
Dynamit Nobel Raleigh, NC	DR
Elma Corporation	EA

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Supplier	*Code*
Empco	EM
EniChem America	EC
Epitaxy	EP
Epitronics	ET
Exsil	EX
Fairchild	FS
FORMOSA SUMCO TECHNOLOGY CORP. [formerly known as Formosa Komatsu Silicon Corporation]	FK
Freiberger Compound	FE
Fujimi Electronic Industry Co. Ltd.	FJ
Fujian Norstel	FN
Furukawa Electric, Ltd.	FC
GlobalWafers Co., Ltd – China [formerly operated under Sino-American Silicon Products Inc.]	KC
GlobalWafers Co., Ltd – Taiwan [formerly known as Sino-American Silicon Products Inc.]	TS
GlobalWafers Co., Ltd – USA [formerly known as Globitech Inc. (USA)]	GU
Haina Semiconductor Co. Ltd.	HN
Hamada	HA
Hitachi	HI
Hitachi Cable, Ltd.	HC
Ibis Technology Corporation	II
Ibis-MEMC	IM
IBM	IB
IBM Canada Ltd (Bromont)	BR
InPact	IP
IntelliEPI IR, Inc.	IR
Intelligent Epitaxy Technology, Inc.	IE
International Semiconductor Products PTE, Inc.	IS
International Silicon Solutions	IT
INTRINSIC	AA
Isiltec GmbH	IC
Japan Energy Corporation	JE
Kawasaki Wafer Technology (Kawatec)	KW
KINIK COMPANY [formerly known as Kinik Precision Grinding Corp.]	KI
Kobe Precision	KP
Komatsu Silicon America, Inc. (obsolete)	KA
Komatsu Silicon U.S.A., Inc. (obsolete)	KS
Kyushu Dentsu Co., Ltd.	KD
Litton Airtron	AR
Lucky Advanced Materials	LU
M/A COM	MA
MCP Wafer Technology Wafer Technology Ltd.	WT

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Supplier	*Code*
MEMC IPOH, Malaysia – A SunEdison Semiconductor Company	PO
MEMC Japan – A SunEdison Semiconductor Company	MJ
MEMC Korea Company – A SunEdison Semiconductor Company	PL
MEMC Kuala Lumpur – A SunEdison Semiconductor Company	KL
MEMC Novara – A SunEdison Semiconductor Company	MN
MEMC Southwest – A SunEdison Semiconductor Company	SW
MEMC-CSMS Electronic Materials, Ltd.	MC
Mimasu Handotai	MR
Mitsubishi Kasei Polytec	MK
Monsanto	MO
Montco Silicon Technologies	ML
Motorola	MT
Mullard	MU
Mycosil	MS
NAMIKI PRECISION JEWEL CO., LTD	NK
Nanolay AG	NA
Norstel AB	NO
North East Silicon Technologies, Inc.	NE
Nikko Materials (relevant business successor of Nippon Mining)	NM
Novotech	NV
Okmetic	OK
Outokumpu Semitronic	OS
Pensilco	PE
Philips	PH
Phoenix Silicon International	PS
PicoPolish	PP
Plan Optik AG	PX
Polishing Corporation of America	PC
Pure Wafer Ltd.	PW
RASA Industries, Ltd.	RA
RCA	RC
Recticon	RE
Rhone Siltec	RS
RS Technologies	RX
Rubicon Technology	RT
Scientech Wafer Technology Corp.	SZ
SEH	SE
SEH America	VA
SEH Isobe	JI
SEH Malaysia	UK
SEH Mimasu	JM
SEH Nagano	JD
SEH Naoetsu	JN

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